

Abstract**Process and Device for Pretreating the Surfaces of Substrates to be Bonded**

- 5 The present invention provides a process and a device for treating the surfaces or bonding surfaces of substrates before bonding the substrates. In accordance with the invention, the surfaces of substrates to be bonded are treated with an atmospheric plasma before bonding. The surfaces of the substrates can thus be cleaned, chemically activated or removed. However, it is also possible to grow a layer by corresponding reactive plasma
- 10 gases. The invention is advantageous in that bonded substrates can be produced in a simple and cost-saving manner, wherein a high adhesive strength can be achieved.